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(54) **HEAT DISSIPATING APPARATUS FOR ELECTRONIC ELEMENTS**

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**ABSTRACT**

Provided is a heat dissipating apparatus for electronic elements which has the minimum size but has improved heat dissipating performance. To this end, the heat dissipating apparatus for electronic elements, according to the present invention, comprises: a heat dissipating housing having an internal space; a shield case formed of a thermally conductive material, wherein the shield case is disposed in the heat dissipating housing and partitions the internal space into a first chamber which is a vacuum space to be filled with a refrigerant and a second chamber which is a non-vacuum space; and a printed circuit board which is disposed in the shield case and has a heat dissipating element. The shield case evaporates the refrigerant by using sensible heat transferred from the heat dissipating element to the shield case and latent heat transferred from the shield case to the first chamber.

